SCAS512E - JUNE 1995 - REVISED OCTOBER 2003

- 2-V to 6-V V_{CC} Operation
- Inputs Accept Voltages to 6 V
- Max t_{pd} of 6.5 ns at 5 V

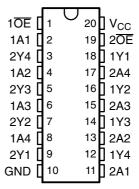
description/ordering information

These octal buffers and line drivers are designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

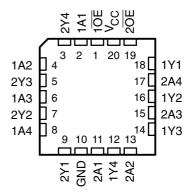
The 'AC240 devices are organized as two 4-bit buffers/drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes inverted data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN54AC240 . . . J OR W PACKAGE SN74AC240 . . . DB, DW, N, NS, OR PW PACKAGE (TOP VIEW)



SN54AC240 . . . FK PACKAGE (TOP VIEW)



ORDERING INFORMATION

T _A	PACKAGI	Εt	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74AC240N	SN74AC240N
–40°C to 85°C	COIC DW	Tube	SN74AC240DW	40040
	SOIC - DW	Tape and reel	SN74AC240DWR	AC240
	SOP - NS	Tape and reel	SN74AC240NSR	AC240
	SSOP – DB	Tape and reel	SN74AC240DBR	AC240
	TOCOD DW	Tube	SN74AC240PW	40040
	TSSOP – PW	Tape and reel	SN74AC240PWR	AC240
	CDIP – J	Tube	SNJ54AC240J	SNJ54AC240J
–55°C to 125°C	CFP – W	Tube	SNJ54AC240W	SNJ54AC240W
	LCCC – FK	Tube	SNJ54AC240FK	SNJ54AC240FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



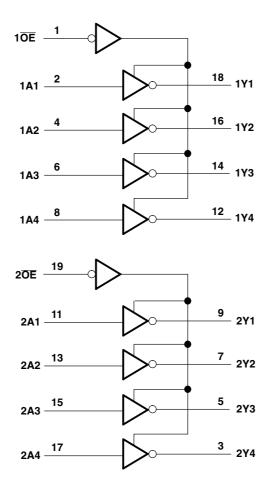
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



FUNCTION TABLE (each buffer)

INPU	JTS	OUTPUT
OE	Α	Υ
L	Н	L
L	L	Н
Н	Χ	Z

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	
Output voltage range, VO (see Note 1)	
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})) ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±200 mA
Package thermal impedance, θ_{JA} (see Note 2):	DB package 70°C/W
, , , , , , , , , , , , , , , , , , , ,	DW package 58°C/W
	N package
	NS package 60°C/W
	PW package 83°C/W
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN54#	C240	SN74A	C240	UNIT
			MIN	MAX	MIN	MAX	UNII
V_{CC}	Supply voltage		2	6	2	6	V
		V _{CC} = 3 V	2.1		2.1		
V_{IH}	High-level input voltage	V _{CC} = 4.5 V	3.15		3.15		V
		V _{CC} = 5.5 V	3.85		3.85		
		V _{CC} = 3 V		0.9		0.9	
V_{IL}	Low-level input voltage	V _{CC} = 4.5 V		1.35		1.35	V
		V _{CC} = 5.5 V		1.65		1.65	
V_{I}	Input voltage		0	V_{CC}	0	V_{CC}	V
Vo	Output voltage		0	V_{CC}	0	V_{CC}	V
		V _{CC} = 3 V		-12		-12	
I_{OH}	High-level output current	V _{CC} = 4.5 V		-24		-24	mA
		V _{CC} = 5.5 V		-24		-24	
		V _{CC} = 3 V		12		12	
I_{OL}	Low-level output current	V _{CC} = 4.5 V		24		24	mA
		V _{CC} = 5.5 V		24		24	
Δt/Δν	Input transition rise or fall rate			8		8	ns/V
T_A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SN54AC240, SN74AC240 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DA	DAMETED	TEST CONDITIONS		T,	գ = 25°C		SN54A	C240	SN74A	C240	UNIT					
PA	RAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP I	MAX	MIN	MAX	MIN	MAX	UNII					
			3 V	2.9			2.9		2.9							
		I _{OH} = -50 μA	4.5 V	4.4			4.4		4.4							
			5.5 V	5.4			5.4		5.4							
.,		$I_{OH} = -12 \text{ mA}$	3 V	2.56			2.4		2.46		.,					
V _{OH}			4.5 V	3.86			3.7		3.76		V					
		$I_{OH} = -24 \text{ mA}$	5.5 V	4.86			4.7		4.76							
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V				3.85									
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V						3.85		<u> </u>					
			3 V			0.1		0.1		0.1						
		I _{OL} = 50 μA	4.5 V			0.1		0.1		0.1	v					
			5.5 V			0.1		0.1		0.1						
. ,		I _{OL} = 12 mA	3 V			0.36		0.5		0.44						
V_{OL}			4.5 V			0.36		0.5		0.44						
		$I_{OL} = 24 \text{ mA}$	5.5 V			0.36		0.5		0.44						
		I _{OL} = 50 mA [†]	5.5 V					1.65								
		I _{OL} = 75 mA [†]	5.5 V							1.65						
	Data inputs	V _I = V _{CC} or GND				±0.1		±1		±1						
l _l	Control inputs	V _I = V _{CC} or GND	5.5 V			±0.1		±1		±1	μΑ					
		$V_O = V_{CC}$ or GND, $V_{I(OE)} = V_{IL}$ or V_{IH}	5.5 V		±	0.25		±5		±2.5	μΑ					
I _{CC}		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		80		40	μА					
C _i		V _I = V _{CC} or GND	5 V		2.5						pF					

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	T _A = 25°C			SN54AC240		SN74AC240		LINUT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}		V	1.5	6	8	1	11	1	9	
t _{PHL}	Α	Y	1.5	5.5	8	1	10.5	1	8.5	ns
t _{PZH}	<u> </u>	V	1.5	6	10.5	1	11.5	1	11	
t _{PZL}	ŌĒ	Υ	1.5	7	10	1	13	1	11	ns
t _{PHZ}	ŌĒ	V	1.5	7	10	1	12.5	1	10.5	no
t _{PLZ}	OE.	ĭ	1.5	7.5	10.5	1	13.5	1	11.5	ns

[‡] For I/O ports, the parameter I_{OZ} includes the input leakage current.

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	$T_A = 25^{\circ}C$			SN54AC240		SN74AC240		UNIT
PANAMETEN	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
t _{PLH}		V	1.5	4.5	6.5	1	8.5	1	7	
t _{PHL}	А	Y	1.5	4.5	6	1	8	1	6.5	ns
t _{PZH}	<u> </u>	V	1.5	5	7	1	9	1	8	
t _{PZL}	ŌĒ	Y	1.5	5.5	8	1	10.5	1	8.5	ns
t _{PHZ}	ŌĒ	V	2.5	6.5	9	1	10.5	1	9.5	no
t _{PLZ}	OE .	ī	2	6.5	9	1	11	1	9.5	ns

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per buffer/driver	$C_L = 50 \text{ pF}, f = 1 \text{ MHz}$	45	pF

PARAMETER MEASUREMENT INFORMATION O 2×VCC **TEST** S1 $\mathbf{500}\,\Omega$ tpLH/tpHL Open **From Output** $\textbf{2} \times \textbf{V}_{\textbf{CC}}$ **Under Test** t_{PLZ}/t_{PZL} Open t_{PHZ}/t_{PZH} $C_L = 50 pF$ **500** Ω (see Note A) Output v_{cc} **LOAD CIRCUIT** Control 50% V_{CC} 50% V_{CC} (low-level enabling) - t_{PLZ} t_{PZL} – Output ≈V_{CC} 50% V_{CC} 50% V_{CC} Input Waveform 1 50% V_{CC} S1 at 2 × V_{CC} t_{PLH} (see Note B) **t**PHL t_{PZH} -– t_{PHZ} Output VOH Waveform 2 $V_{OH} - 0.3 V$ 50% V_{CC} $50\% \; V_{\text{CC}}$ Output 50% V_{CC} S1 at Open V_{OL} ≈0 V (see Note B) **VOLTAGE WAVEFORMS VOLTAGE WAVEFORMS**

NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







9-Mar-2021

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-87550012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87550012A SNJ54AC 240FK	Samples
5962-8755001RA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8755001RA SNJ54AC240J	Samples
5962-8755001SA	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8755001SA SNJ54AC240W	Samples
SN74AC240DBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC240	Samples
SN74AC240DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC240	Samples
SN74AC240DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC240	Samples
SN74AC240N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74AC240N	Samples
SN74AC240NE4	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74AC240N	Sample
SN74AC240NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC240	Sample
SN74AC240PW	ACTIVE	TSSOP	PW	20	70	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC240	Samples
SN74AC240PWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC240	Samples
SN74AC240PWRE4	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC240	Samples
SNJ54AC240FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87550012A SNJ54AC 240FK	Samples
SNJ54AC240J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8755001RA SNJ54AC240J	Samples
SNJ54AC240W	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8755001SA SNJ54AC240W	Samples

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

PACKAGE OPTION ADDENDUM



9-Mar-2021

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54AC240, SN74AC240:

■ Catalog: SN74AC240

Automotive: SN74AC240-Q1, SN74AC240-Q1

Military: SN54AC240

NOTE: Qualified Version Definitions:





9-Mar-2021

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

All difficulties are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC240DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AC240DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74AC240NSR	so	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74AC240PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC240DBR	SSOP	DB	20	2000	853.0	449.0	35.0
SN74AC240DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74AC240NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AC240PWR	TSSOP	PW	20	2000	853.0	449.0	35.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
 C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.

 D. Index point is provided on cap for terminal identification only.

 E. Falls within Mil—Std 1835 GDFP2—F20



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-150.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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